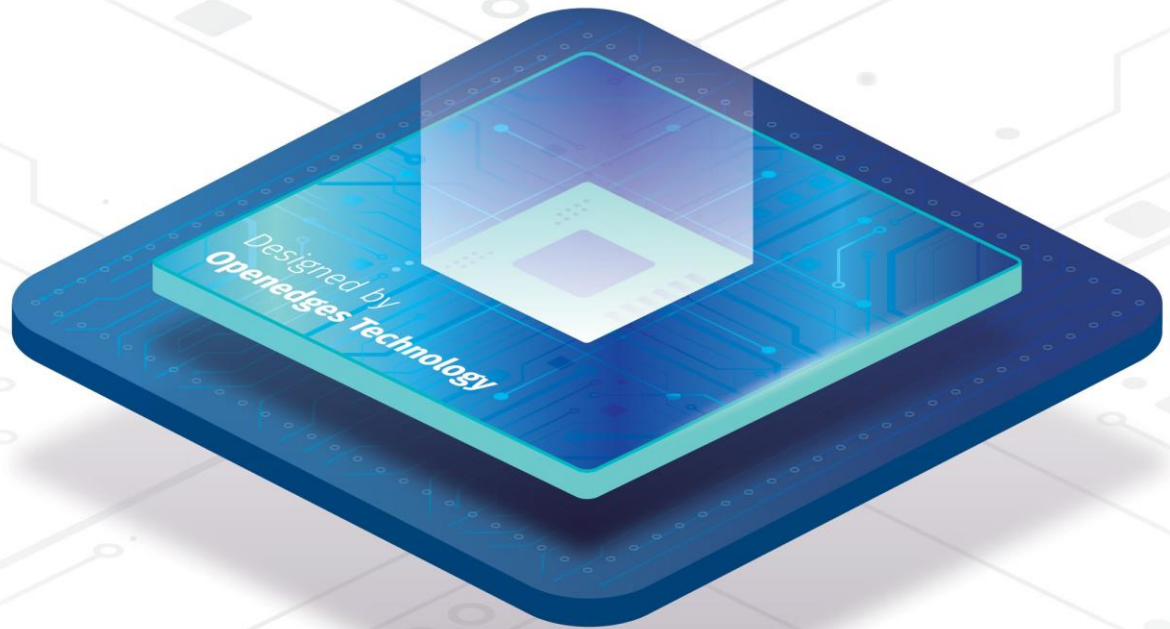


# *AI for Everyone, Everywhere*



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# The Future of AI Computing

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**02**

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as Korea's most renowned  
AI semiconductor IP  
design company

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Performance

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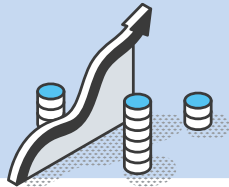


# Openedges Technology at a Glance

## 99%

Sales Revenue CAGR(Last 5yrs)

\* FY2019~2023



## 55

Number of Cumulative License Agreements

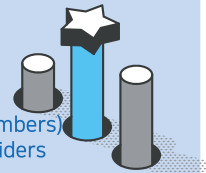
\* As of March 31st



## 143

Global R&D Engineers

\* 86% of total employees(166 members)  
\* Largest among Korean IP Providers



## AI for Everyone, Everywhere

**OPENEDGES**  
Technology, Inc.

## 30+

Number of Clients

\* Secured global top-tier customers such as Samsung Electronics, SK Hynix, and Micron



## 20+

IP products available for sale

\* Number of IP Products within 4 IP categories



## 4

Global R&D Centers

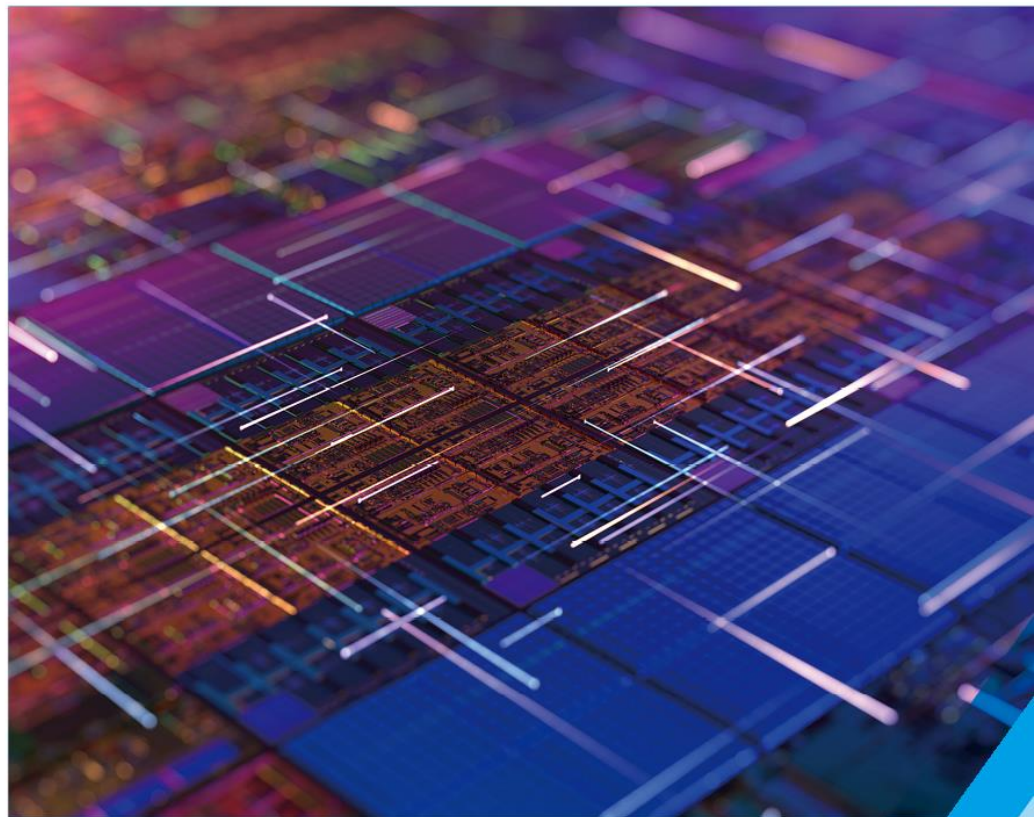
\* Korea, US, Canada & Japan





# Prologue

OPENEDGES Technology's Business Areas



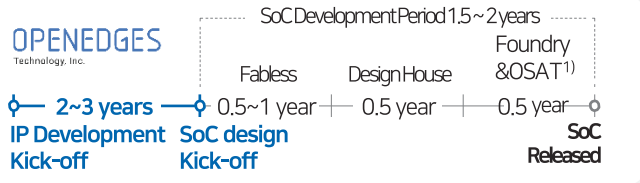
# OPENEDGES Technology's Business Areas ①

**Semiconductor IP is a ready-made solution requiring high-level technologies that enable faster development of SoC (System on Chip) such as AI semiconductors, reduce costs, and mitigate the risk of failure risks in development that can cost \$100 million**



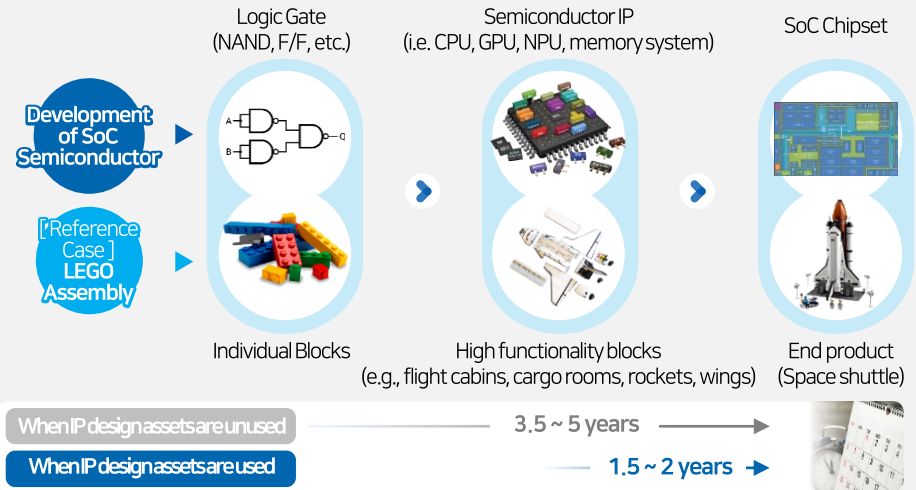
## What is Semiconductor IP?

Previously designed/verified function blocks, such as CPU, GPU, and NPU, that can be embedded in SoC

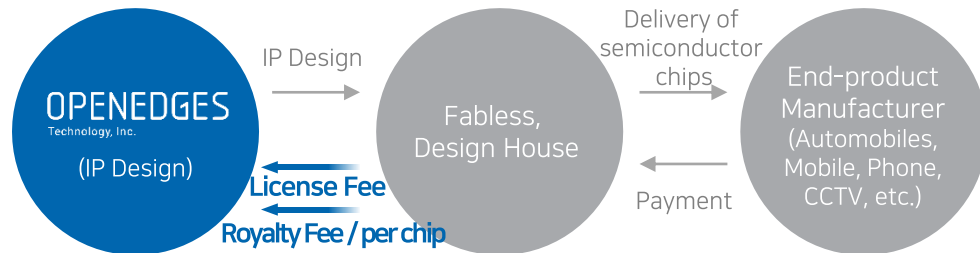


※ Note 1) Outsourced Semiconductor Assembly and Test (Packaging and backend company)

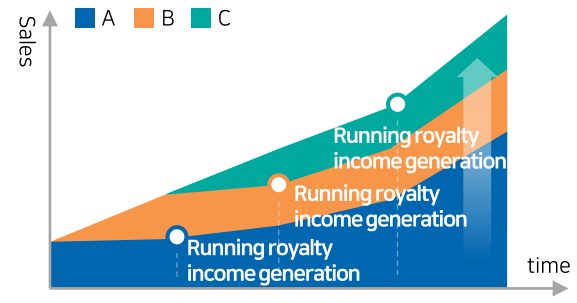
**Reduction in SoC design time and cost for fabless companies**



## Semiconductor IP Business Profit Structure

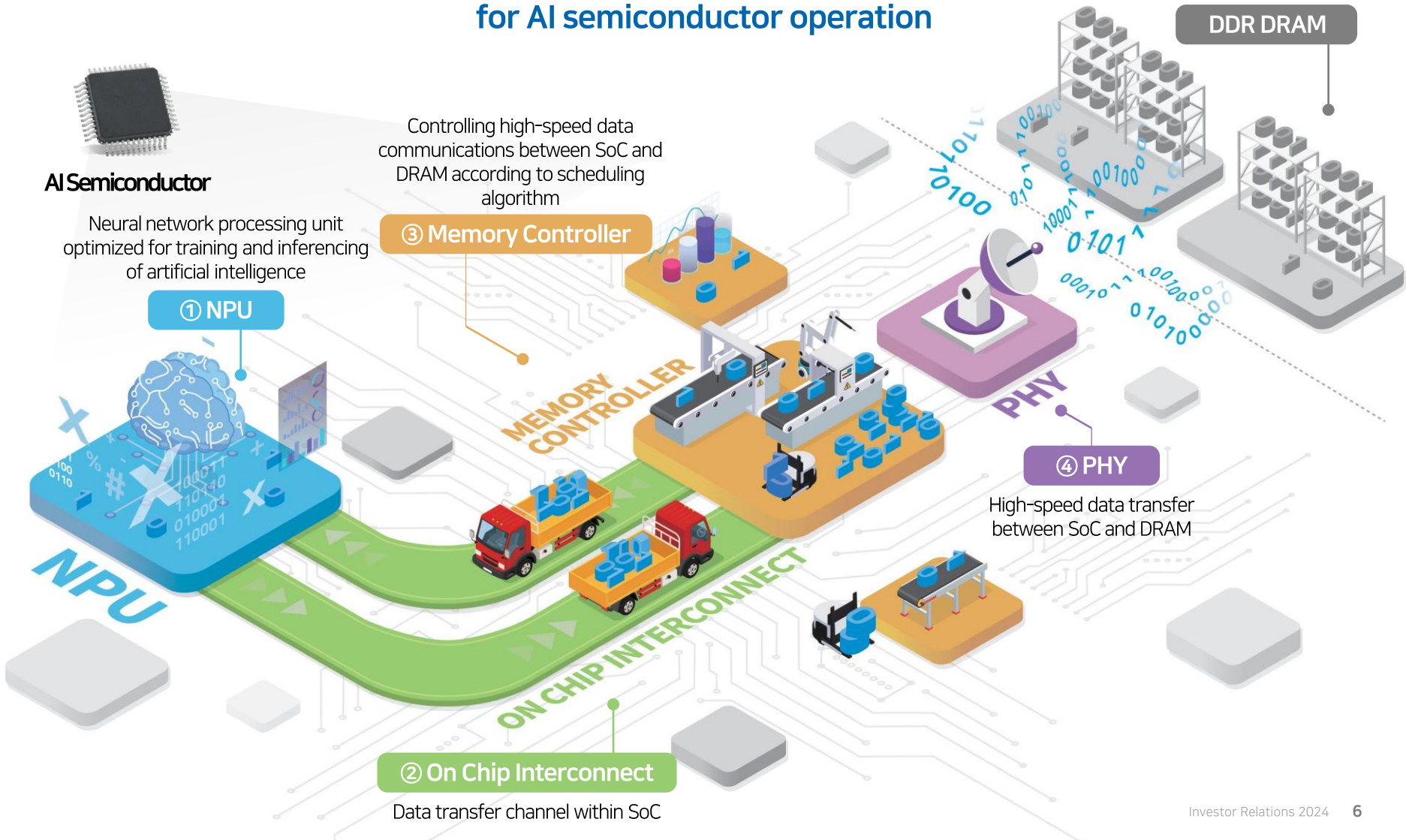


※ The semiconductor IP industry has been oligopolistic, dominated by a few market players due to high technical barriers to entry.



# OPENEDGES Technology's Business Areas ②

## Design and provision of integrated IP solution that serves as a basis for AI semiconductor operation

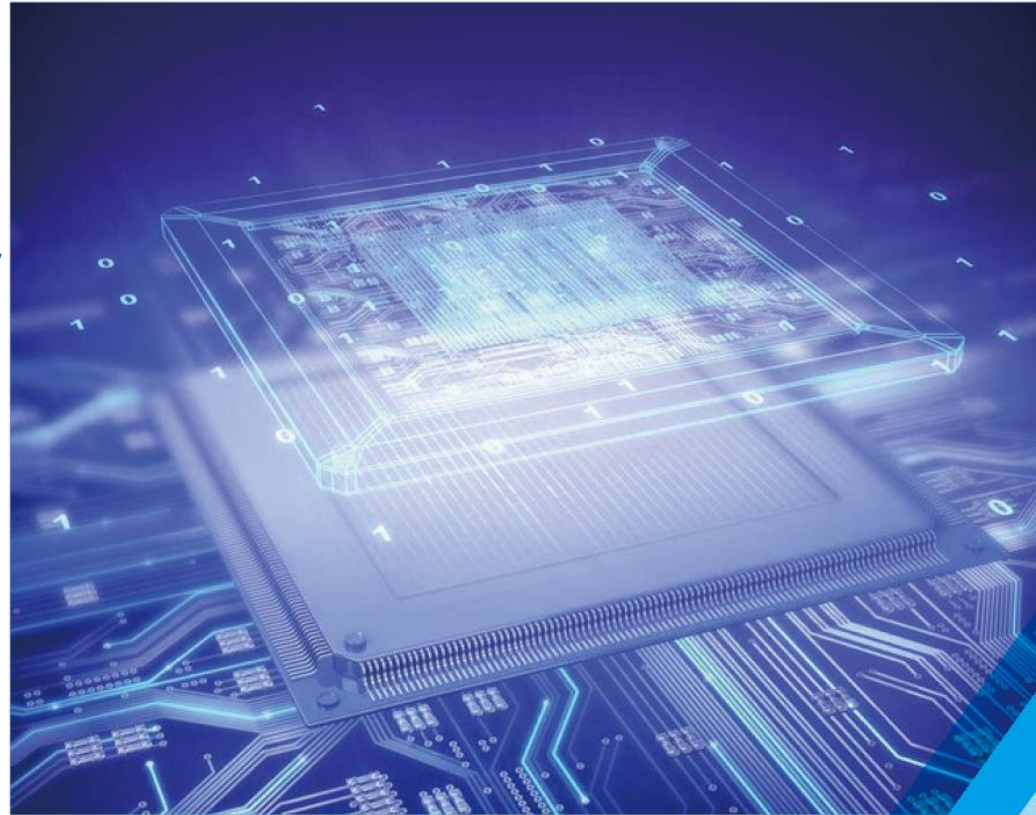




# 01

## Structural Development of System Semiconductor Market

- 01. Growth of AI Semiconductor & IP Market
- 02. Roles of Semiconductor IP Design Company



# 01 | Growth of Global System Semiconductor Market

**Contrary to memory semiconductors, system semiconductors are continuing their steady growth**

## Prospects for Global Semiconductor Market 2024

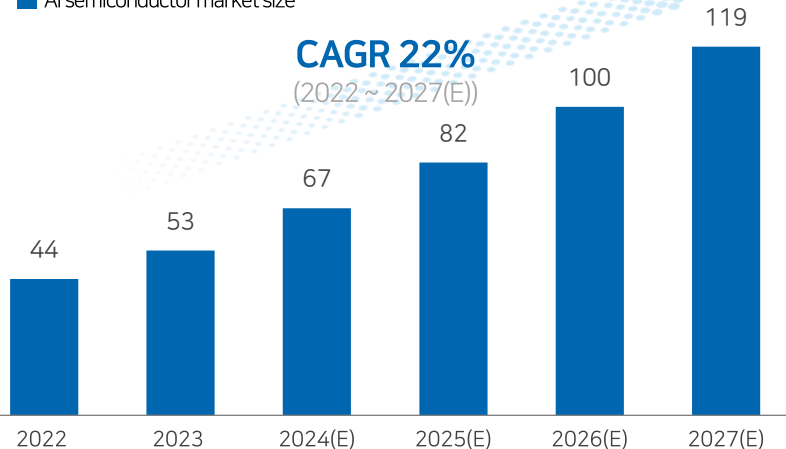


※ Source: WSTS, Nov 2023 (Excluding Optoelectronics, Discrete Semiconductors and sensors)

## Prospects of Global AI Semiconductor Market

(Unit: \$ B)

■ AI semiconductor market size



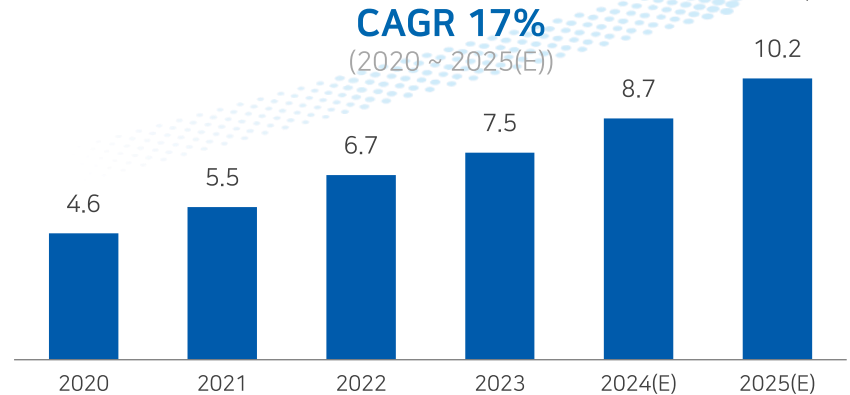
※ Source: AI Semiconductor (Gartner, Aug 2023), Estimated by company

## Global Semiconductor IP market forecast

Company	2023 Sales (\$ M)	CAGR (2018-2022)
arm	2,938	10%
SYNOPSYS®	1,542	17%
cādence®	391	11%
OPENEDGES	15	99%
Others		14%
<b>Total</b>		<b>16%</b>

■ Semiconductor IP market size

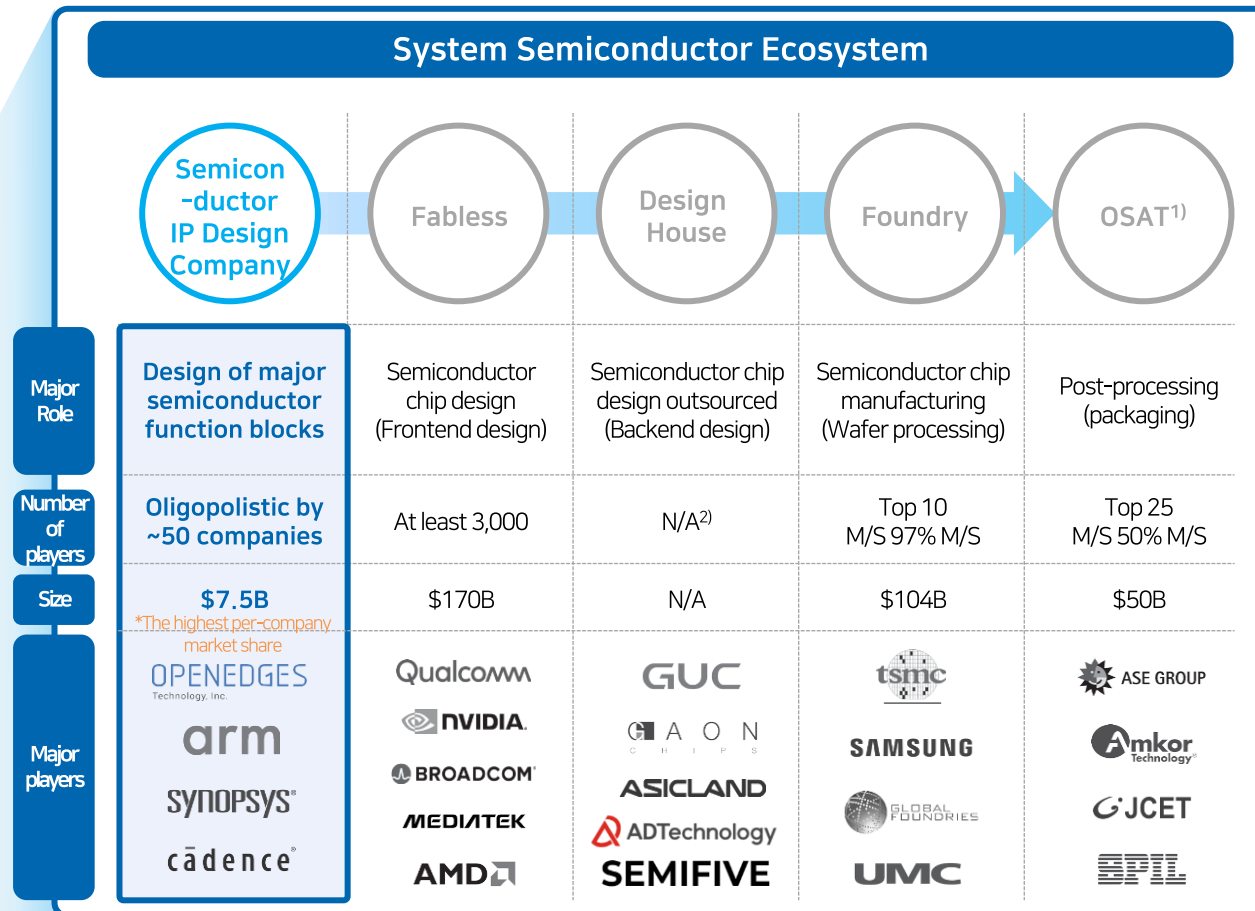
(Unit: \$ B)



※ Source: Design IP revenues (Ipnest, Apr 2023), Press Clipping

# 03 | Roles of Semiconductor IP Design Companies

Semiconductor IP companies aim to develop and supply function blocks as needed by Fabless and Design House in a proactive manner.



**Reasons for IP oligopoly**

**Higher demand for proven IPs**

**IP companies with proven IPs are in high demand due to the rising entry barriers**

- Requires highly proficient technical personnel
- Requires R&D investments for at least 3 years

※ Note 1) (Outsourced) Semiconductor Assembly and Test: Semiconductor package assembly and test company that is responsible for performing post-processing after wafer process

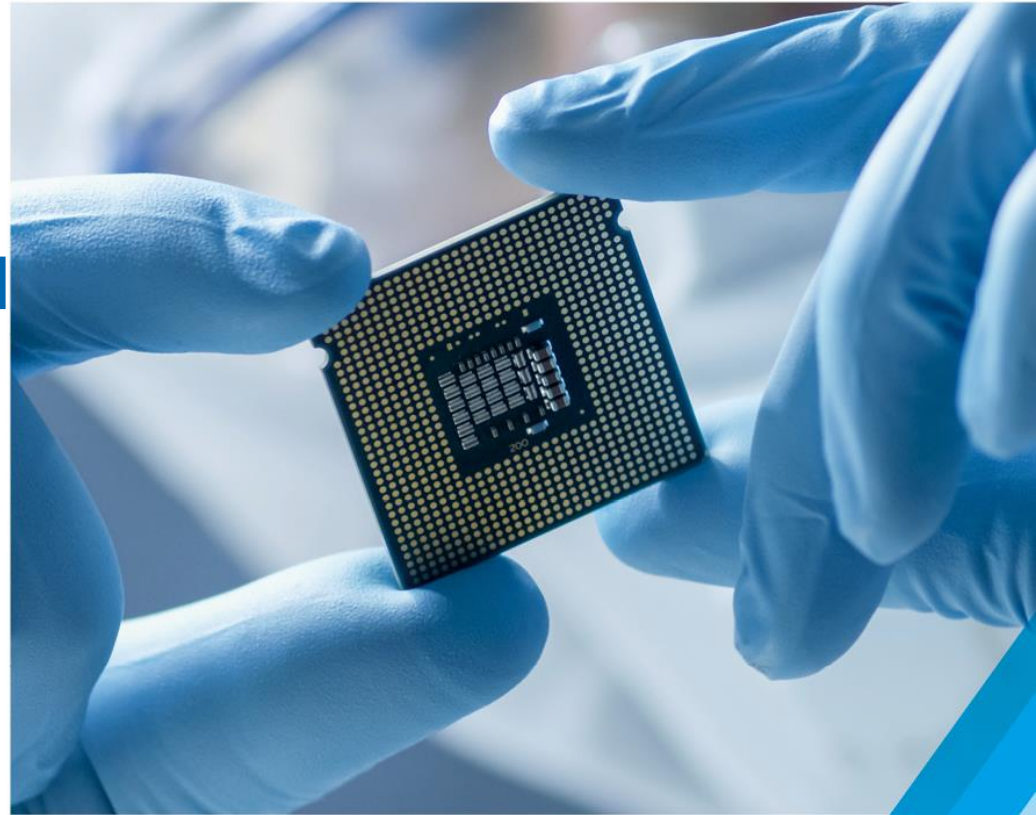
Note 2) Design House market does not have a reliable market size data as it is in its initial formation stage.



# 02

## OPENEDGES Technology, as Korea's most renowned AI semiconductor IP design company

01. The Overview of OPENEDGES's Core Competitiveness
02. A Global Team of Professionals
03. Industry's Highest Technological Competitiveness
04. Verified Global Track Records
05. Business Partnership with Global Enterprises



# 01 | The Overview of OPENEDGES' Core Competitiveness

**OPENEDGES holds the key success factors**  
to become a global leader in the AI semiconductor IP market

01



A Global team of Professionals



02



Industry's highest technological competitiveness



03



Verified global track records



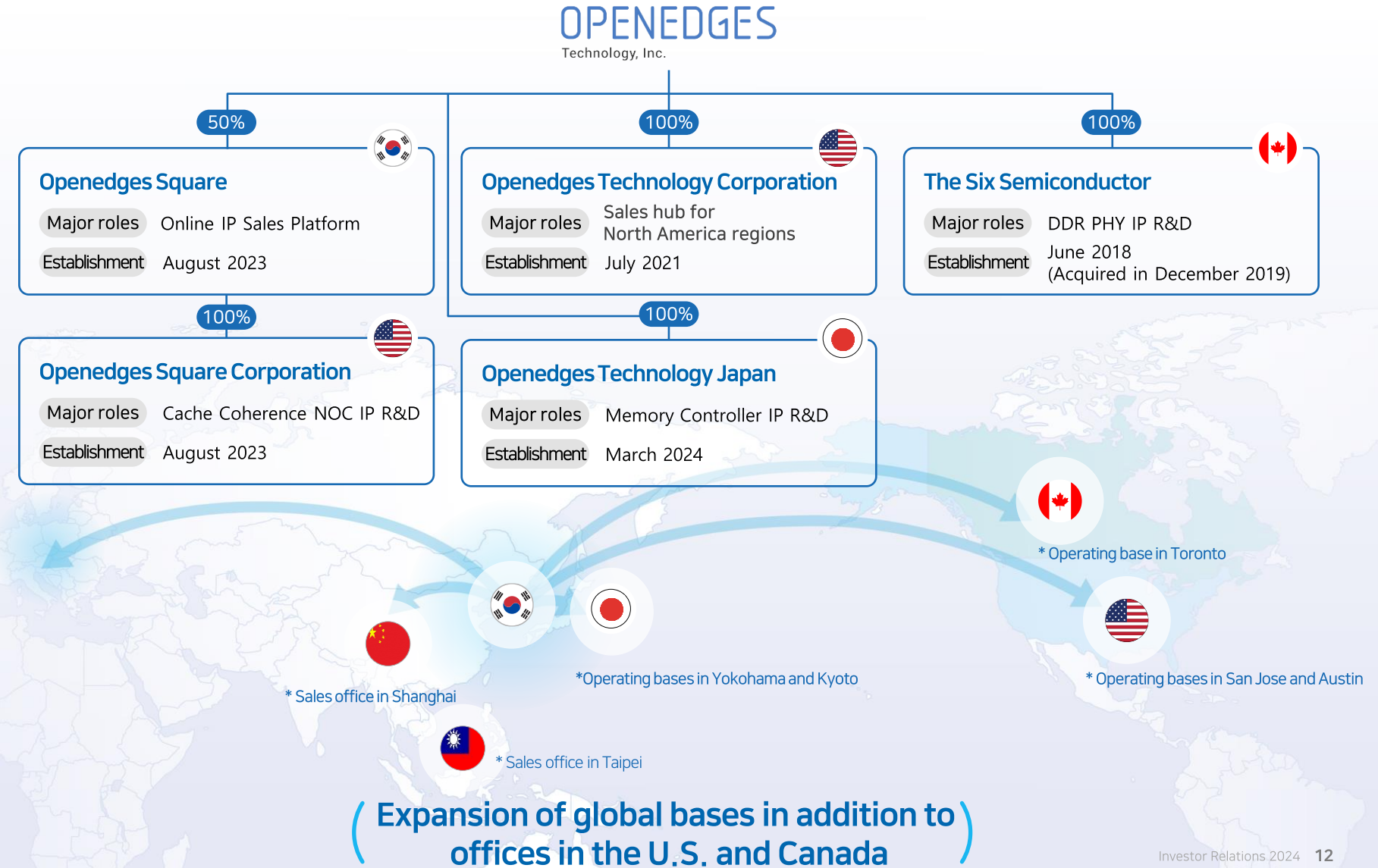
04



Strategic partnership with global enterprises



# 02 | A Global Team of Professionals – Global Presence





# 02 | A Global Team of Professionals

## Leadership of industry-leading experts with over 20 years of experience from Samsung Electronics/SK Hynix, and more.



### R&D personnel

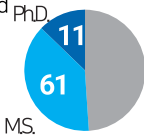
Among the total personnel (166 team members)

**86%**

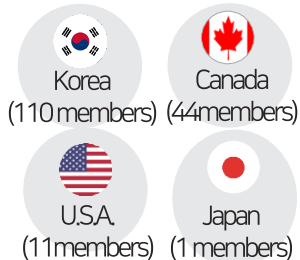



Percentage of Ph.D. and MS. degree holders (72 members) among the R&D personnel

**50%**




### Status of Each Country

**Sean Lee**  
Representative Director / CEO

**SAMSUNG** | **SAMSUNG ADVANCED INSTITUTE OF TECHNOLOGY**

Ph.D. Candidate in Electrical and Computer Engineering, Seoul National University  
 '17-Present: Representative Director, OPENEDGES Technology, Inc.  
 '08~'15: Principal Researcher, Samsung Electronics (Exynos Development)  
 '07~'08: Samsung Advanced Institute of Technology



**Jake Choi**  
NPU Team Head

**SK hynix** | **SAMSUNG**


Ph.D. in Electrical and Computer Engineering, Purdue University  
 '18 ~ Present: NPU Team Head, OPENEDGES Technology, Inc.  
 '15~'18: Principal Researcher, SK Hynix  
 '09 ~ '14: Architecture Lab Part Head, Samsung Electronics



**Richard Fung**  
TSS/CEO

**AMD** | **PERASO**


M.S. in Electrical and Electronic Engineering, Univ. of Toronto  
 '18 ~ Present: CEO, The Six Semiconductor  
 '12 ~'18: Silicon Director, etc., Peraso Technologies  
 '00 ~'11: PHY Analog Design Manager, AMD



**Roger Jennings**  
OSC / VP of Engineering

**ARTERIS IP** | **AMD** | **intel**


M.S. in Electrical and Electronic Engineering, Univ. of Memphis  
 '22 ~ Present: VP of Engineering, OPENEDGES SQUARE  
 '20 ~ '22: Arteris IP Senior Director of Engineering  
 '00 ~ '21: Intel, Juniper Networks, AMD etc.



**Cody Hwang**  
R&D Center Head / CTO / Co-founder

**Codeholics/ codeholics** | **대우전자** | **Chips&Media**


M.S. in Electrical Engineering, Seoul National University  
 • 2017- Present: CTO, OPENEDGES Technology, Inc.  
 • 2010-2015: CTO, CodeHolics  
 • 2000-2010: Daewoo Electronics, Chips & Media



**Takashi Yamada**  
OTJ/Reginal VP

**socionext** | **Panasonic**


B.A. in Electrical Engineering, University of Tokyo Denki  
 '24~ Present: Openedges Technology Japan Regional VP  
 '15~'24: SOCIONEXT Inc., Principal Engineer  
 '88~'15: PANASONIC Corporation



**Ricky Lau**  
TSS/CTO

**AMD** | **SYNOPSYS**

M.S. in Electrical and Electronic Engineering, Univ. of Toronto  
 '18-Present: CTO, The Six Semiconductor  
 '14 ~ '18: PHY Digital Design Engineer, Synopsys  
 '03 ~ '14: PHY Analog Design Engineer, etc., AMD



**Niranjan Cooray**  
OSC/Chief Architect

**intel**

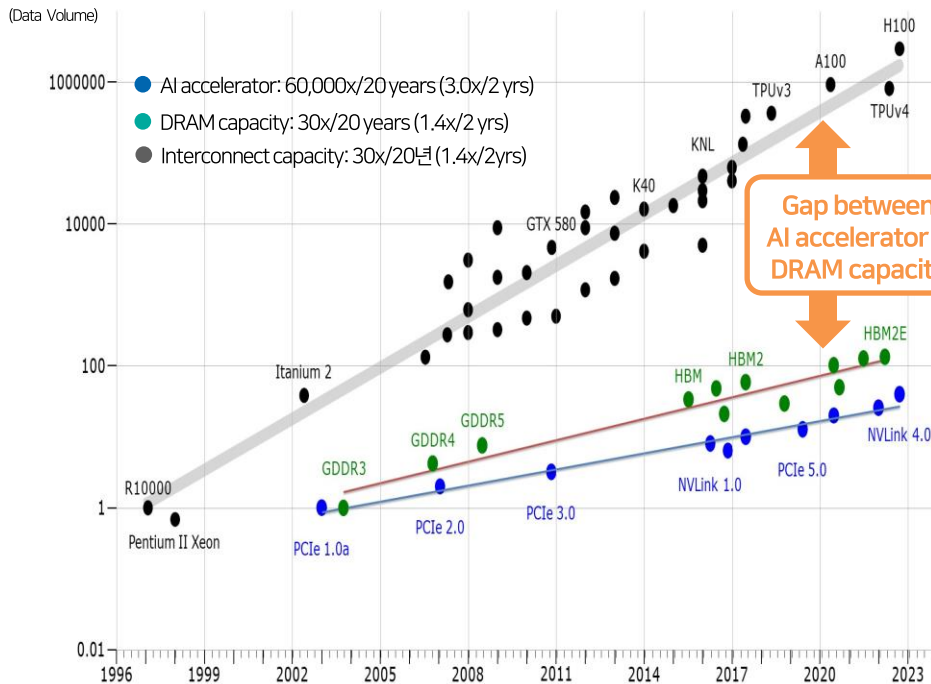
M. S. in Electrical and Computer Engineering, Northeastern University  
 '24 ~ Present: OPENEDGES SQUARE, Chief Architect  
 '95 ~ '24: Intel, Principal Engineer

※ As of the end of Mar. 2024

# 03 | Industry's Highest Technological Competitiveness ①

**AI semiconductors are characterized as 'Data Intensive Computing'**  
 → **Most optimize NPU and memory systems in edge AI with limited resources**  
 OPENEDGES is the only global leading AI semiconductor IP platform provider

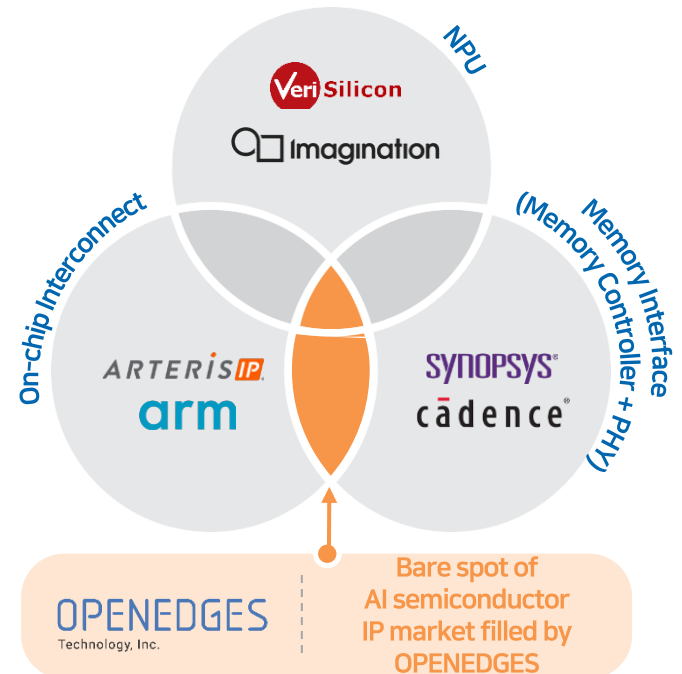
The gap between the required data processing volume and the capacity provided by DRAMs has increased due to the development of AI accelerator technologies



※ Source: AI And Memory Wall By Riselab

## AI Platform IP for Edge Computing

OPENEDGES is globally the only company that is capable of supplying NPU IP (the core of AI semiconductors) and memory system IP (functions as the 'Back Bone' for all semiconductors) at the same time.



# 03 | Industry's Highest Technological Competitiveness ③

## Leading the market through the development of cutting-edge technology

Division	IP	Description	Development status	Remark
AI Platform IP Solution for Edge Computing	ENLIGHT™ (Neural Processing Unit)	ENLIGHT™-Light (0.25 ~ 2 TOPS)	Now	Lightweight IoT applications (Keyword recognition, security camera application)
		ENLIGHT™-Classic (2 ~ 16 TOPS)	Now	Intermediate IoT applications (ADAS)
		ENLIGHT™-Pro (16 ~ 250 TOPS)	<b>Now (Released in Apr. '24)</b>	<b>Automotive high-performance applications (Level 3 or higher self-driving vehicle application)</b>
		ENLIGHT™-Hyper (250 ~ 1000 TOPS)	In the future	Automotive high-performance applications (Level 4 or higher self-driving vehicle application)
Total Memory System Solution IP (ORBIT™)	OMC™ (DDR Memory Controller)	DDR4/3, LPDDR4X/4/3	Now	
		LPDDR5X/5/4X/4	Now	Current Mainstream Technology
		HBM3	Now	Server and ultra-high-performance products
		DDR5	Now	Current Mainstream Technology
		GDDR6	Now	High-performance AI product
		GDDR7	In the future	Next-generation High-performance AI product
		LPDDR6	<b>In the process</b>	<b>Next-generation Mainstream Technology</b>
	OPHY™ (DDR PHY)	LPDDR4X/4	Now	TSMC 22nm Nodes
		LPDDR5X/5/4X/4	Now	TSMC 16nm Nodes
		LPDDR5X/5/4X/4	Now	TSMC 12nm Nodes
		GDDR6	Now	TSMC 12nm Nodes
		LPDDR5X/5/4X/4	Now	TSMC 6/7nm Nodes
		HBM3	Now	TSMC 6/7nm Nodes
		DDR5	<b>Near future(~'25)</b>	<b>TSMC 5nm Nodes</b>
		LPDDR6	In the future	TSMC 4nm(or less) Nodes
		LPDDR3, DDR4/3	Now	Samsung 28nm Nodes
		LPDDR4X/4, LPDDR5/4X/4	Now	Samsung 14nm Nodes
		LPDDR5/4X/4	Now	Samsung 8nm Nodes
		LPDDR5X/5/4X/4	Now	Samsung 5nm Nodes
		LPDDR6	<b>Near future(~'25)</b>	<b>Samsung 4nm Nodes</b>
	GDDR7	In the future	-	
	OIC™ (On-Chip-Interconnect)	OIC™	Now	Non- Cache-Coherent NoC
OIC™-AI		<b>In the process</b>	<b>Cache-Coherent NoC</b>	

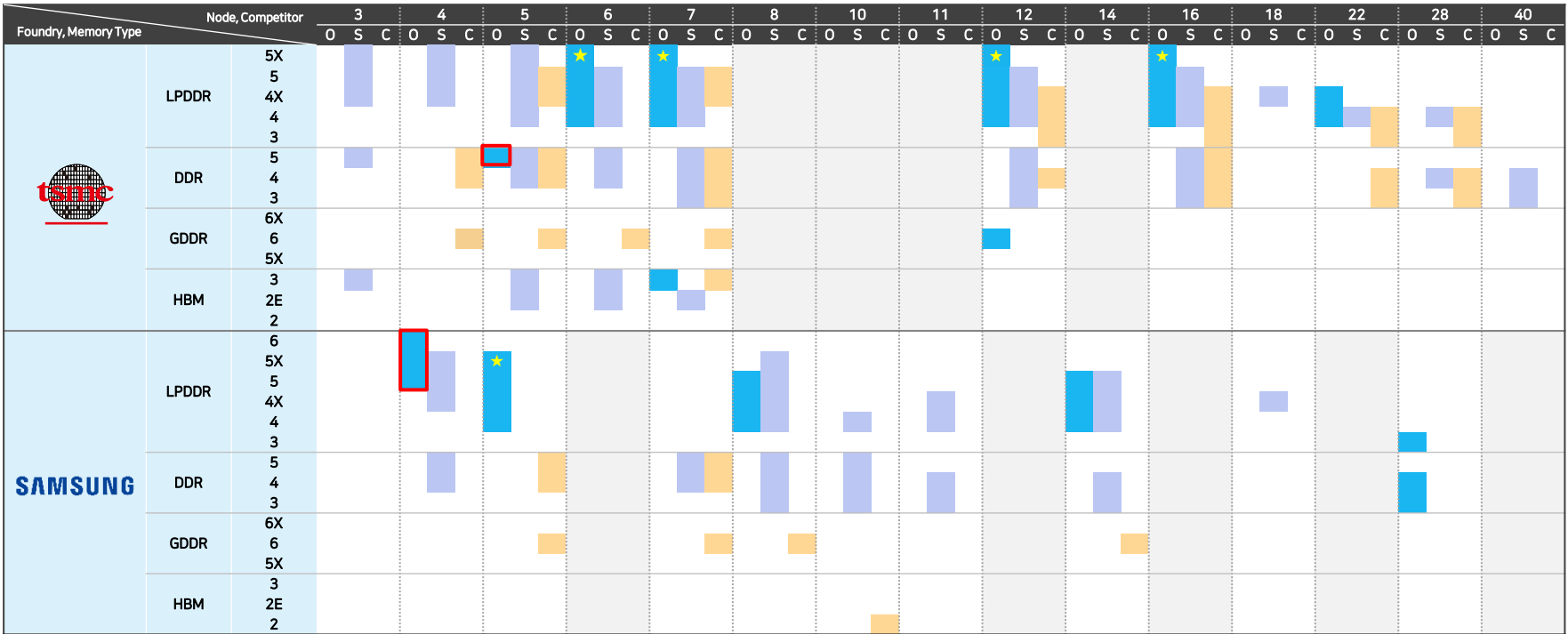


# 03 | Industry's Highest Technological Competitiveness ④

Concentrate on areas that major global competitors cannot cover & expand M/S

## DDR PHY IP Competition status

Openedges    Synopsys    Cadence



IP to be developed, \*: Sole Provider

M/S expansion strategy

- ✓ Synopsys and Cadence are focusing on TSMC 5nm and below leading-edge processes
- ✓ OE is the only one provides LPDDR5X/5 PHY IP for various nodes
- ✓ OE is expecting customer pool through the development of PHY IP for SF 4nm & TSMC 5nm processes
- ✓ OE's PHY IP requires area less than 50% compared to competitors by providing through the test chips

# 03 | Industry's Highest Technological Competitiveness ⑤

## Maximize first-mover advantage of AI semiconductor integrated IP solutions

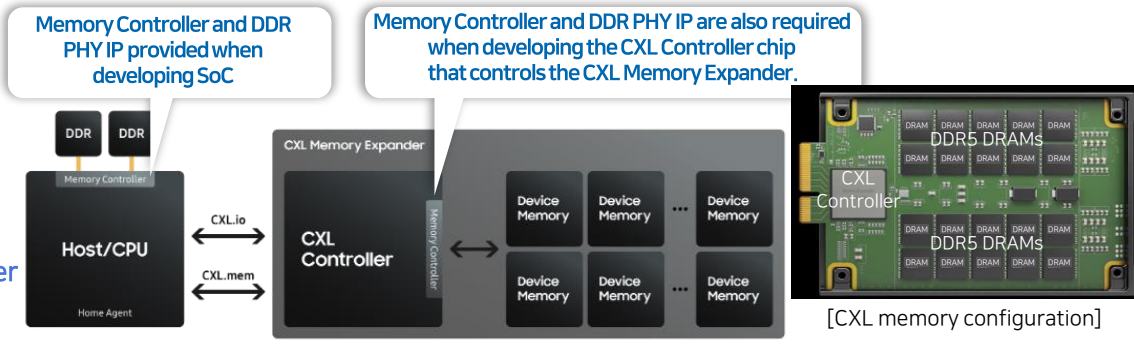
Expected Release Schedule		2021		2022		2023		2024		2025	
		1H	2H	1H	2H	1H	2H	1H	2H	1H	2H
ENLIGHT™ Neural Processing Unit		NPU v1.0		NPU v2.0				NPU v3.0 Autonomous Driving		NPU v4.0 Autonomous Driving	
		[Performance] 0.25~2 TOPS [TargetProduct] Light-weight IoT application products (keyword recognition, security camera application)		[Performance] 2~16 TOPS [TargetProduct] Medium or higher level of IoT application products (autonomous driving auxiliary application)		[Performance] 16~250 TOPS [TargetProduct] High-performance application products for vehicles (Application of autonomous driving vehicles with Level 3 or higher)		[Performance] 250~1,000 TOPS [TargetProduct] High-performance application products for vehicles (Multi-Die version application of autonomous driving vehicles with Level 4 or higher)			
OIC™ On-Chip Interconnect	Non-Cache Coherent NOC	OIC v.1.X						OIC v.2.0			
	Cache Coherent NOC									OIC-AI	
OMC™ Memory Controller		GDDR6	LP5X/5 /4X/4		HBM3	DDR5				LP6	
OPHY™ DDR PHY	SAMSUNG		LP4/4X/5 (14nm)				LP5X/5/4X (5nm)			LP6 (4nm)	
	tsmc			LP4/4X/5 GDDR6 (12nm)	LP4/4X/5 (22nm)	HBM3 LP4X/5/5X (6/7nm)		LP5X/5/4X (12/16nm)		DDR5 (5nm)	
OUC (TBD) Controller Die to Die (Chiplet)									UCle v1.1 Controller (AXI streaming)		UCle v1.1 Controller (Full spec.)
OPHY™ PHY Die to Die (Chiplet)	SAMSUNG										OPHY-D2D (5/8nm)
	tsmc										OPHY-D2D (6nm)

# 03 | Industry's Highest Technological Competitiveness ⑥

Leading the next generation of high value-added semiconductor technology expected to grow rapidly

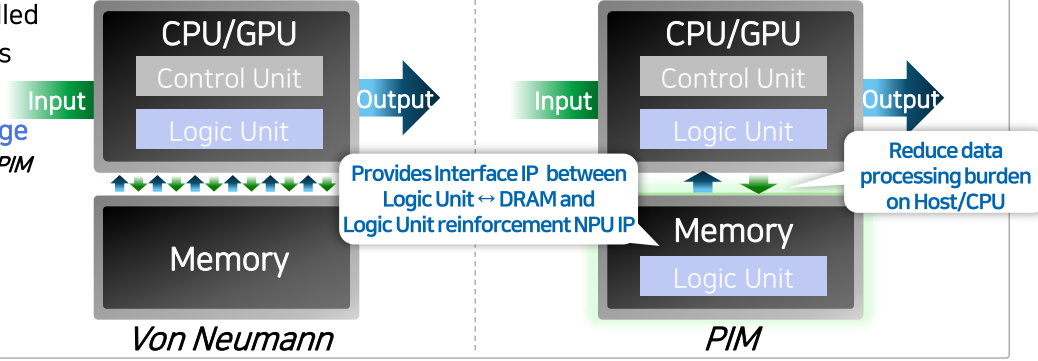
## CXL (Compute Express Link)

- CXL interface can flexibly expand memory without limitations on memory standard capacity and performance dependent on existing Host/CPU
  - Effectively supports data intensive high-performance calculations such as AI chips
- supplies IP for the design of the CXL Controller chip, the core of the CXL Memory Expander.



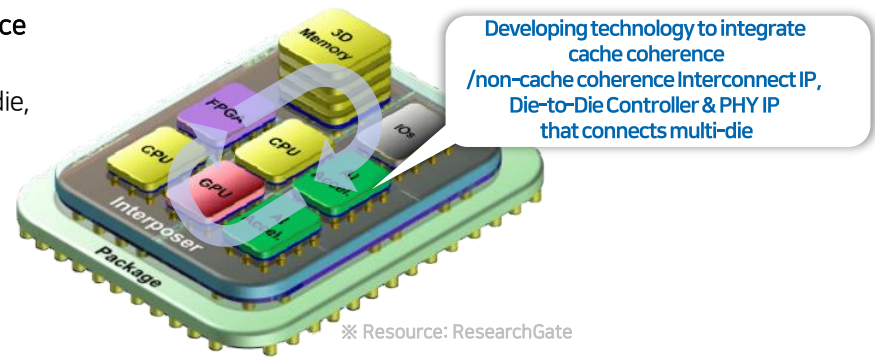
## PIM (Process-in-Memory)

- PIM off-loads some of the computational functions handled by the Host/CPU (von Neumann structure) and processes them in the PIM.
  - Speed ↑, Power ↓ by simultaneous calculation & storage
  - ※ Samsung is using HBM and SK Hynix is using GDDR6 for developing PIM
- Supplies Memory System IP, which is responsible for the data interface between Logic Unit and DRAM in PIM semiconductors, and NPU IP required to improve the performance of Logic Unit.



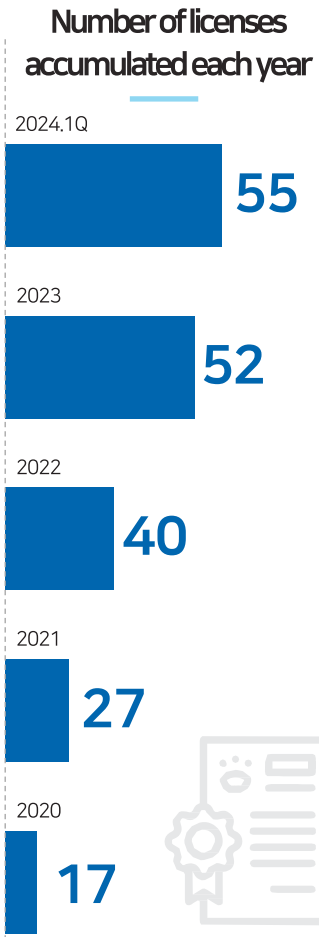
## Chiplet

- A chiplet is a SoC that is manufactured by dividing high-performance SoC functions into multiple dies and then packaging them.
  - SoC development cost & Risk ↓: Optimal process selection for each die, net die increase by reducing chip area
  - Development period ↓: Independent design for each die, use of previously verified chiplets possible
- provides 'On-chip & Chip-to-Chip Interconnect IP Solution' that can implement multi-die interconnect technology beyond single-die standard interconnect IP.



# 04 | Verified Global Track Records

Expanding global track record as value recognized as the essential solution in various industries



**Intelligent security camera**

VISIONEXT nextchip  
eyenix PnpNetwork Technologies, Inc.

**Autonomous driving/ In-vehicle face recognition**

AISIN Telechips  
nextchip GAON CHIPS

**Server/storage devices**

SAMSUNG SK hynix  
ASICLAND GLENFLY  
Global company / novachips

**IoT / Mobile**

JLQ TECHNOLOGY MONTAGE Technology  
SENSCOMM GCT

**AI**

Micron StarFive 赛昉科技  
SemiFive DeepX

**Others (drones, PC, etc.)**

LX Semicon EUL  
ASICLAND

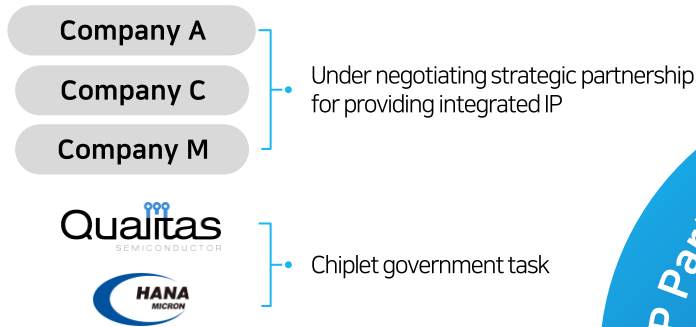
\* 57 licenses as of May 16th, 2024



# 05 | Business Partnership with Global Enterprises

## Securing stable IP demands + Proactive response to advanced technologies and market trends

### Strengthening partnerships with IP companies



### Securing references with top-tier customers



### Strengthening partnerships with Foundries

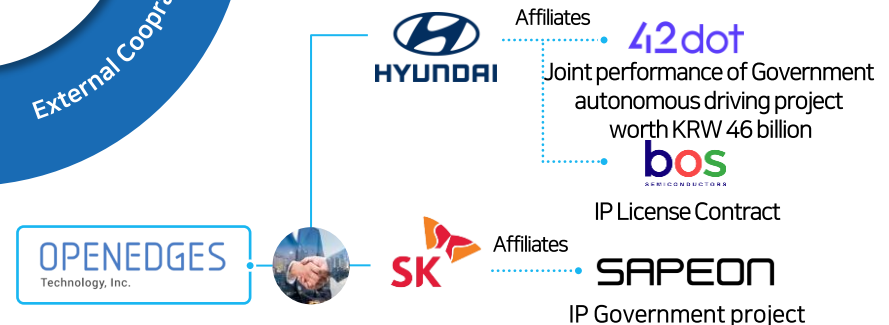


- 2 clients who licensed OE IPs are preparing mass production at TSMC
- OE is targeting to join as a formal partner in the TSMC IP Alliance Program



- Selected as SAFE\* IP Partner in 2018
- Expanding IP cooperation in the fields of memory interface IP

### Strengthening external cooperation



\* SAFE (Samsung Advanced Foundry Ecosystem)

# 03

## '24 1Q Business Performance

01. Sales
02. Operating Profit(Loss)
03. Contract Status
04. Sales revenue Breakdown
05. Financial Summary

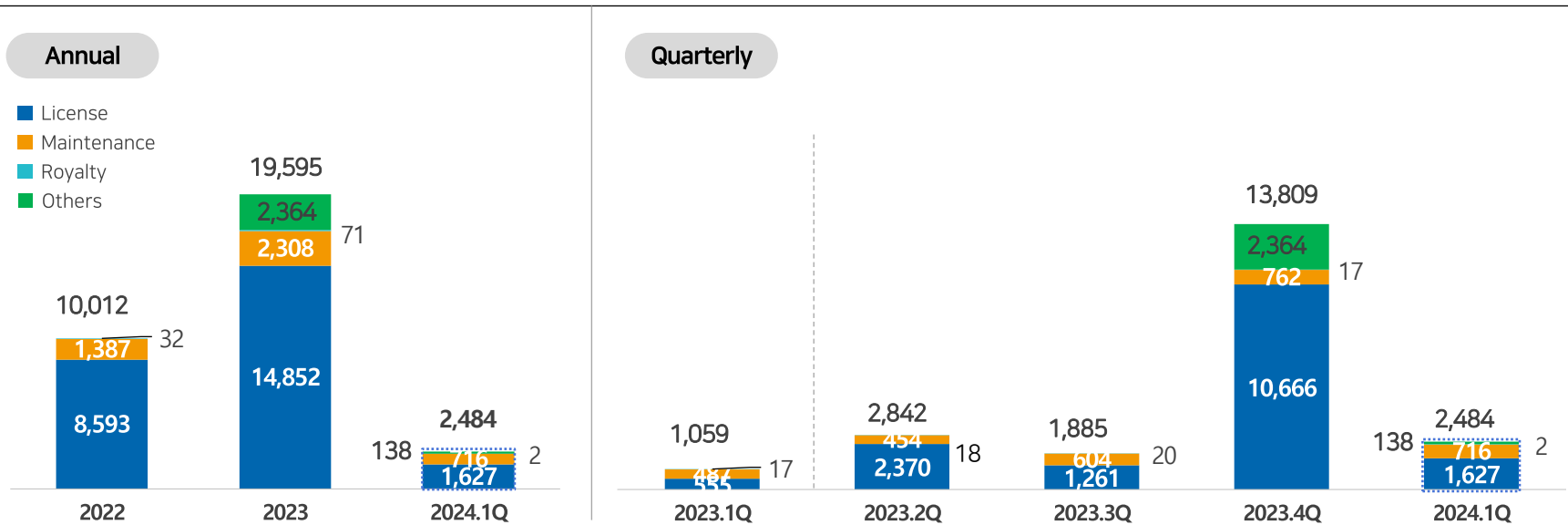


# 01 | Sales Revenue

**Recorded KRW 2.5 billion due to delays in new contracts ( $\Delta 82\%$ , QoQ).  
**Significant growth compared to the same period last year (135%, YoY)  
 and expecting growth after closing license contracts currently under negotiation.****

## Sales status

(Unit: KRW 1 million)



### Sales Analysis

- ✓ **License** : Due to Delay of new contracts, Sales decreased compared to 4Q23, but increased YoY
- ✓ **Maintenance**: Sales are being generated from a total 27 projects
- ✓ **Royalty**: Expected to continue to grow in the future due to increased mass production of chips by customers
- ✓ **Others**: Sales for operational and technical support services for Openedges Square

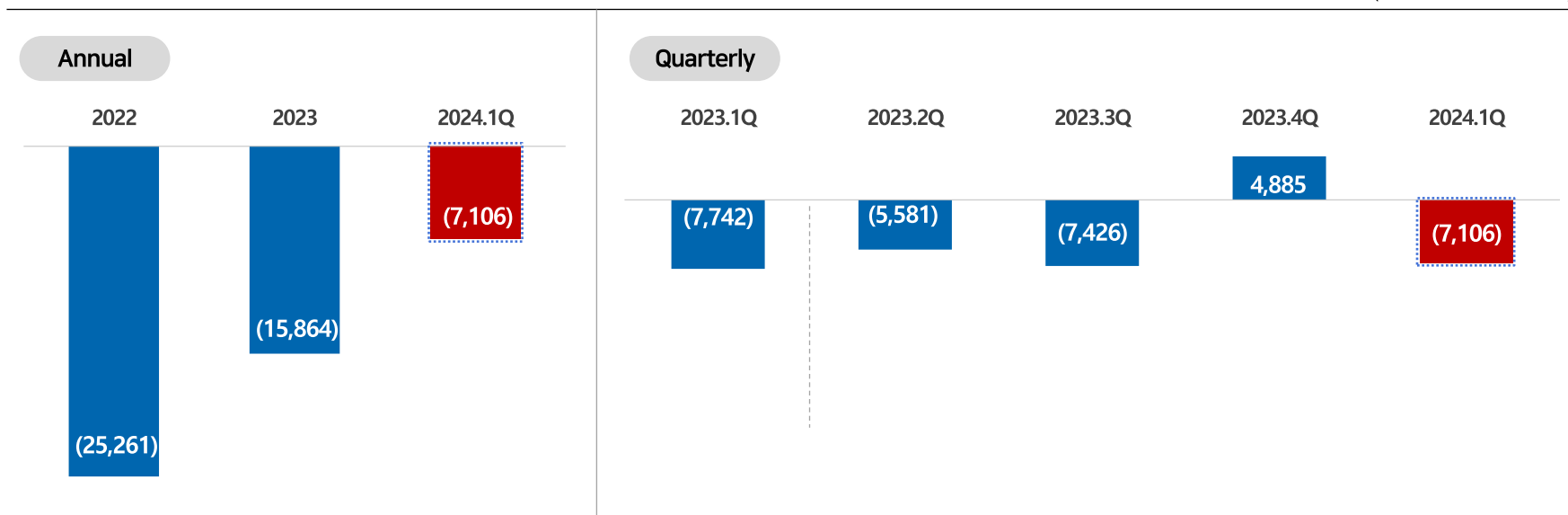
## 02 | Operating Profit(Loss)

An operating loss of KRW 7.1 billion due to a decrease in sales, while managing R&D costs at KRW 8 to 9 bn. Quarterly.

Securing contracts under discussion will improve profitability in the near term

### Operating Profit(Loss)

(Unit: KRW 1 million)



#### Operating Profit Analysis

- ✓ Loss due to decline in license sales, expecting turnaround when securing orders under negotiation
- ✓ Most of the R&D expenses are for developing new IP, are being managed stably at around KRW 8 to 9 billion per quarter without burdening large one-off costs.
- ✓ As a number of license contracts are currently being discussed, expecting that sales will increase, and profitability will continue to improve.



## 03 | Contract Status

**'24. 1Q recorded unsatisfactory performance due to the delay in signing the license contracts  
However, expecting to increase license contracts from '24.2Q**

### Contract Status

(Unit: USD 1 million)

- **'24. 1Q: 3 new license contracts, worth \$1.6M**
  - The average price per contract is 0.5M\$,
  - a low-performance/low-price IP-centered contracts
- **As of May 16th: 5 cumulative license contracts, worth \$3.2M**
  - \* '24.1Q Earning release date
  - The average price per contract is \$0.6M
  - Price slightly higher compared to the first quarter.

#### Contract status

(Unit: case/\$M)	'24. 1Q	As of 16.May (Cumulative)	FY2023
Numbers	3	5	12
Sum of Contract value	\$1.6M	\$3.2M	\$15.5M
Average price of Contract	(\$0.5M)	(\$0.6M)	(\$1.3M)

### Performance Analysis and outlook

#### '24 1Q Results

- **Delay in signing high-performance/high-price IP contract**
  - High-performance SoC projects considering Samsung 5nm and TSMC 6/7 nm are delayed
- **Delay in completion of customization design project**
  - Negotiation about customized IPs that supports the latest DRAMs such as HBM3 and DDR5 took longer than expected

#### 2024 Outlook

- **Expect high growth in normal license sales and improve profitability**
  - Steady improvements in opportunities to secure contracts from 2H23
  - Sales and profitability growth through high-performance IP contracts
- **Expand due to demand for next-generation and customization**
  - In addition to CXL, expanding collaboration to reduce the performance gap between AI semiconductors and DRAM, such as PIM and Chiplet
  - In addition to normal licenses, we plan to respond quickly to customization IP licenses with global top-tier companies

## 04 | Financial Statements(Consolidated)

### Statement of Financial Position

(Unit: KRW 1 million)

	1Q24	2023	2022	2021
Current Assets	25,086	29,843	44,304	29,020
Non-current Assets	12,218	14,849	9,552	7,077
<b>Total Assets</b>	<b>37,305</b>	<b>44,692</b>	<b>53,855</b>	<b>36,097</b>
Current Liabilities	18,939	19,750	18,318	9,171
Non-current Liabilities	4,103	4,371	3,288	6,374
<b>Total Liabilities</b>	<b>23,041</b>	<b>24,121</b>	<b>21,606</b>	<b>15,545</b>
Capital	2,173	2,146	2,116	1,653
Capital Surplus	99,315	98,259	96,376	58,927
Other Capital	3,293	3,577	2,026	3,007
Retained earnings	-90,517	-83,412	-68,269	-43,035
<b>Total Equity</b>	<b>14,263</b>	<b>20,571</b>	<b>32,249</b>	<b>20,553</b>

### Income Statements

(Unit: KRW 1 million)

	1Q24	4Q23	Change	Change(%)
<b>Sales Revenue</b>	<b>2,484</b>	<b>13,809</b>	<b>-11,325</b>	<b>-82.0</b>
<b>Operating Expenses</b>	<b>9,589</b>	<b>8,924</b>	<b>665</b>	<b>7.5</b>
R&D Cost	7,543	6,439	1,104	17
Selling General & Admin. Expense	2,046	2,485	-439	-18
<b>Operating Profit</b>	<b>-7,106</b>	<b>4,885</b>	<b>-11,991</b>	<b>N/A</b>
Financial Income	380	357	23	6.4
Financial Expenses	416	303	113	37.3
Other Income	37	1,061	-1,024	-96.5
Other Costs	0	0	0	0.0
<b>Profit before Income Tax Expense</b>	<b>-7,106</b>	<b>5,999</b>	<b>-13,105</b>	<b>N/A</b>
Income Tax Expense	0	358	-358	N/A
<b>Net Income</b>	<b>-7,106</b>	<b>5,642</b>	<b>-12,748</b>	<b>N/A</b>

# 05 | Financial Summary

## Financial Summary

(Unit: KRW 1 Million)

Consolidated	2018	2019	2020	2021	1Q22	2Q22	3Q22	4Q22	2022	1Q23	2Q23	3Q23	4Q23	2023	1Q24
<b>Revenue</b>	<b>588</b>	<b>1,238</b>	<b>1,089</b>	<b>5,186</b>	<b>3,033</b>	<b>3,975</b>	<b>1,577</b>	<b>1,426</b>	<b>10,012</b>	<b>1,059</b>	<b>2,842</b>	<b>1,885</b>	<b>13,809</b>	<b>19,595</b>	<b>2,484</b>
License fee	524	990	660	4,342	2,798	3,619	1,175	1,001	8,593	555	2,370	1,261	10,666	14,852	1,627
Maintenance	65	249	423	808	230	350	392	415	1,387	487	454	604	762	2,308	716
Royalty			6	35	5	7	10	10	32	17	18	20	17	71	2
Others													2,363	2,363	138
<b>Cost and Expense</b>	<b>1,029</b>	<b>4,422</b>	<b>8,896</b>	<b>16,241</b>	<b>5,792</b>	<b>7,293</b>	<b>7,844</b>	<b>14,344</b>	<b>35,273</b>	<b>8,801</b>	<b>8,422</b>	<b>9,311</b>	<b>8,924</b>	<b>35,458</b>	<b>9,589</b>
R&D Cost	208	2,347	6,623	10,654	3,937	5,361	6,063	12,349	27,710	7,052	6,546	7,146	6,439	27,184	7,543
Selling General & Admin Expense	821	2,075	2,273	5,587	1,855	1,932	1,782	1,995	7,563	1,749	1,876	2,165	2,485	8,275	2,046
<b>Operating Income</b>	<b>△441</b>	<b>△3,183</b>	<b>△7,807</b>	<b>△11,055</b>	<b>△2,759</b>	<b>△3,317</b>	<b>△6,267</b>	<b>△12,918</b>	<b>△25,261</b>	<b>△7,742</b>	<b>△5,581</b>	<b>△7,426</b>	<b>4,885</b>	<b>△15,864</b>	<b>△7,106</b>
<b>Net Profit before Corporate Tax Costs</b>	<b>△355</b>	<b>△8,487</b>	<b>△18,729</b>	<b>△14,524</b>	<b>△2,906</b>	<b>△3,398</b>	<b>△6,181</b>	<b>△12,362</b>	<b>△24,846</b>	<b>△7,634</b>	<b>△5,559</b>	<b>△7,317</b>	<b>6,000</b>	<b>△14,510</b>	<b>△7,106</b>
<b>Net Income</b>	<b>△374</b>	<b>△8,487</b>	<b>△18,729</b>	<b>△14,608</b>	<b>△2,906</b>	<b>△3,398</b>	<b>△6,178</b>	<b>△12,745</b>	<b>△25,227</b>	<b>△7,631</b>	<b>△5,557</b>	<b>△7,310</b>	<b>5,642</b>	<b>△14,856</b>	<b>△7,106</b>

※ Numbers are based on consolidated financial statements.